

# ISB-3110 8085 Central Processor Card

#### **FEATURES**

- Full STD BUS Compatibility
- Fully Buffered Signals for System Expandability
- Up to 8K Bytes EPROM Capacity
- Up to 4K Bytes Static RAM Capacity
- Jumper Selectable (2716 or 2732 EPROMS)
- Full Memory Decoding Capability
- Full Bus Arbitration Circuitry
- Three Independent Timer/Counter Channels with Interrupting Capability
- Programmable Power-on Restart
- Power-on Reset and Pushbutton Reset Input
- 6.55 MHz Crystal Oscillator Frequency
- Internal/External Clock Selection
- Tri-state Address, Data and Control Bus
- Single +5V Supply

#### GENERAL DESCRIPTION

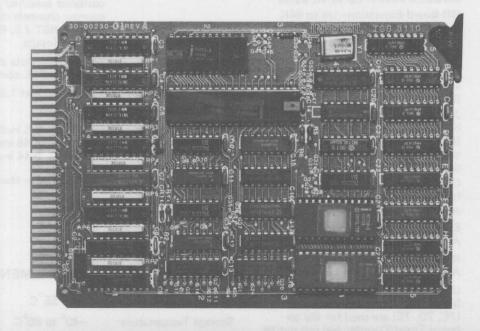
The ISB-3110 is a 8085 based STD BUS Microprocessor Card with 300ns clock time. The entire 8085-CPU Instruction Set can be used for programming without restriction. All signals to and from the STD BUS (address, data, and control) are fully tri-state buffered. Bus arbitration logic ensures proper arbitration between on-board vs. off-board memory, I/O, or interrupt acknowledge operations.

On-board static RAM memory in 1K Byte increments up to a maximum of 4K are provided. The popular 2114 (1K x 4) static RAM with 200ns access time is used. Two 24-pin sockets are provided for EPROM memory. Up to 4K Bytes of EPROM memory are available using 2716's (2K x 8) or up to 8K using 2732's (4K x 8).

Memory mapping for on-board RAMs and EPROMs is jumper selectable and can be mapped in 4K blocks anywhere in the 64K address field in 4K increments. The on-board RAMs and EPROMs can also be totally bypassed and removed from the card

An on-board counter timer circuit provides three independent channels that provide counting and timing functions with interrupting capability and daisy chain priority arbitration. Timer counter interrupts utilize RST 7.5, 6.5 and 5.5 by connecting them to out 2, 1, or 0 of the timer counter.

Both on-board power-on reset and off-board pushbutton reset are implemented. The CPU on reset will start at 0000<sub>H</sub> or can be programmed to jump to any location within the address field. If the latter is chosen, 3 bytes of the first EPROM on the board are used to store the jump address. After reading the starting address, the circuitry disables the EPROM or maps it at other preassigned locations other than 0000<sub>H</sub>. Jumper options include: CPU clock (internal/external), timer counter clock by channel (internal/external), on-board RAM starting address (anywhere in the 64K address field in 4K increments), on-board EPROM starting address (anywhere in the 64K address field in 4K increments), reset restart address (anywhere within on-board memory address range), EPROM selection (2716 or 2732).



INTERSIL, INC., Systems Division, 1275 Hammerwood Avenue, Sunnyvale, CA 94086 Printed in U.S.A. © Copyright 1980, Intersil, Inc., All Rights Reserved.

(408) 743-4442 TWX: 910-339-9369

# ISB-3110

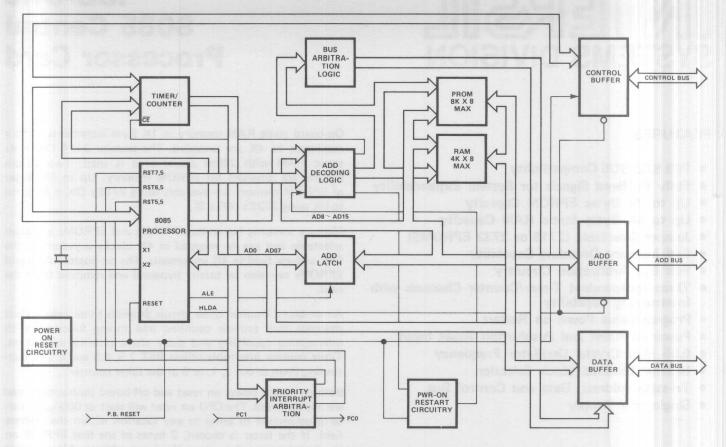


FIGURE 1. ISB-3110 Block Diagram

	TIONS

Word Size:

8-Bit Data Bus

Instruction: 8, 16, 24 Bits

Clock Period (T State):

300ns

Memory Capacity:

On-Board EPROMs-Up to 8K

Bytes

On-Board RAMs-Up to 4K Bytes Off-Board Expansion-Up to 64K Bytes, with Customer Specified Combination of RAMs, ROMs,

EPROMs.

Memory Mapping:

On-Board EPROMs: Jumper Selectable 2716 (2K Bytes) or 2732 (4K

Bytes).

Jumper selectable for any 4K boundary within 64K address field. If 2732 is used, two 4K EPROMs can be mapped independently from each other within 64K address field. On-Board RAMs: Jumper selectable

for any 4K boundary within 64K

address field.

Memory Speed:

EPROM: 2716 or 2732 Access time: 400ns max.

RAM: Dynamic or Static Access time: 400 ns max.

I/O Capacity:

Up to 256 Bytes can be decoded offboard. The three port addresses, (7C, 7D, 7E) are used for the onboard Timer/Counter and can not be used for any off-board peripherals.

I/O Addressing: On-Board programmable Timer

PORT ADDRESS (HEX) CHANNEL

7C 0 7D 1 7E

Interrupts:

Multi-level vector interrupt with interrupt request originating from customer specified I/O only. Timer/ counter channels interrupt CPU through RST 7.5, RST 6.5,

RST 5.5 inputs.

Interface:

All Address, Data and Command signals are TTL compatible.

Power Requirements:

+5 VDC ±5% at 1.5 amps max.

Mating Connector:

See Table 1

Card Dimensions:

Height: 6.5 inches (16.51 cm) Width: 4.48 inches (11.38 cm)

Thickness: 0.44 inches (1.12 cm)

(See Figure 3 For More Details)

## **ENVIRONMENTAL REQUIREMENTS**

Operating Temperature: 0° to 55°C

Storage Temperature:

 $-40^{\circ}$  to  $80^{\circ}$ C

Relative Humidity:

0% to 90% without condensation

TABLE 1. ISB-3110 Compatible Mating Connectors

INTERFACE	NO. OF PAIRS/PINS	CENTERS	CONNECTOR TYPE	VENDOR	VENDOR PART NO.
STD BUS	28/56	0.125 in.	Solder Tail	Viking Winchester	VH28/ICNK5 2HW28 D0-111
STD BUS	28/56	0.125 in.	Wire Wrap	Viking Winchester	VH28/ICHD5 HW28 D0-111

TABLE 2. STD BUS Organization and Specifications (With Pin Definitions)

The STD BUS pinout is organized into five functional groups:

Logic Power Bus
Pins 1–6
Pins 7–14
Address Bus
Pins 15–30
Control Bus
Pins 31–52
Auxiliary Power Bus
Pins 53–56

	COMPONENT SIDE			CIRCUIT SIDE			
PIN	MNEMONIC	SIGNAL FLOW	DESCRIPTION	PIN	MNEMONIC	SIGNAL FLOW	DESCRIPTION
1	+5V	In	+5 Volts DC (Bussed)	2	+5V	In	+5 Volts DC (Bussed)
3	GND	In	Digital Ground (Bussed)	4	GND	In	Digital Ground (Bussed)
5	-5V	In	-5 Volts DC	6	-5V	In	-5 Volts DC
7	D3	In/Out	Low Order Data Bus	8	D7	In/Out	High Order Data Bus
9	D2	In/Out	Low Order Data Bus	10	D6	In/Out	High Order Data Bus
11	D1	In/Out	Low Order Data Bus	12	D5	In/Out	High Order Data Bus
13	D0	In/Out	Low Order Data Bus	14	D4	In/Out	High Order Data Bus
15	A7	Out	Low Order Address Bus	16	A15	Out	High Order Address Bus
17	A6	Out	Low Order Address Bus	18	A14	Out	High Order Address Bus
19	A5	Out	Low Order Address Bus	20	A13	Out	High Order Address Bus
21	A4	Out	Low Order Address Bus	22	A12	Out	High Order Address Bus
23	A3	Out	Low Order Address Bus	24	A11	Out	High Order Address Bus
25	A2	Out	Low Order Address Bus	26	A10	Out	High Order Address Bus
27	A1	Out	Low Order Address Bus	28	A9	Out	High Order Address Bus
29	A0	Out	Low Order Address Bus	30	A8	Out	High Order Address Bus
31	WR	Out	Write to Memory or I/O	32	RD	Out	Read to Memory or I/O
33	IORQ	Out	I/O Address Select	34	MEMRQ	Out	Memory Address Select
35	IOEXP	In/Out	I/O Expansion	36	MEMEX	In/Out	Memory Expansion
37	REFRESH	Out	Refresh Timing	38	MCSYNC	Out	CPU Machine Cycle Sync
39	STATUS 1	Out	CPU Status	40	STATUS 0	Out	CPU Status
41	BUSAK	Out	Bus Acknowledge	42	BUSRQ	In	Bus Request
43	INTAK	Out	Interrupt Acknowledge	44	INTRO	In	Interrupt Request
45	WAITRO	In	Wait Request	46	NMIRQ	In	Non-Maskable Interrupt
47	SYSRESET	Out	System Reset	48	PBRESET	In	Push Button Reset
49	CLOCK	Out	Clock from Processor	50	CNTRL	In '	AUX Timing
51	PCO	Out	Priority Chain Out	52	PCI	In	Priority Chain In
53	AUX GND	In	AUX Ground (Bussed)	54	AUX GND	In	AUX Ground (Bussed)
55	AUX+V	In	AUX Positive (+12 Volts DC)	56	AUX-V	In	AUX Negative (-12 Volts DC

TABLE 3. ISB-3110 STD BUS Signal Functions

SIGNAL	PIN NO.	FUNCTIONAL DESCRIPTION	
+5V	1 & 2	+5 Logic Voltage (V <sub>CC</sub> ) — Main logic voltage lines (+5 volts). Both pins are bussed together for current capacity.	
GND	3 & 4	Logic Ground — Ground for logic power. Both pins are bussed together for current capacity.	
-5V	5 & 6	-5 Logic Voltage — Both pins are bussed together for current capacity.	
D0-D7	7–14	Data Bus — An 8-Bit bidirectional tri-state bus. (Bidirectional means signals may flow either into or out of any card on the Bus). Direction of data is normally controlled by the processor card via the Control Bus. The data direction is normally affected by such signals as Read (RD), Write (WR) and Interrupt Acknowledge (INTAK).	
		The Data Bus uses high-level active logic levels. All cards are required to release the bus to a high impedance state when not in use. The Processor card releases the data bus in response to Bus Request (BUSRQ) input from an alternate system controller, as in DMA transfers.	
A0-A15	15-30	$Address\ Bus-A$ 16-bit tri-state high-level active bus. The address will originate at the processor card or a bus controlling device. The processor card releases the Address Bus in response to a Bus Request ( $\overline{BUSRQ}$ ) input from an alternate controller.	
		The Address Bus provides 16 address lines for decoding by either memory or I/O. Memory request ( $\overline{\text{MEMRQ}}$ ) and I/O request ( $\overline{\text{IORQ}}$ ) control lines are used to distinguish between the two operations.	
WR	31	Write to Memory or $I/O-A$ tri-state, active-low control line that indicates the BUS holds value data to be written in the addressed memory or output device.	
RD	32	Read from Memory or I/O — A tri-state, active-low control line that indicates the processor or other bus controlling device wants to read data from memory or an I/O device. The selected I/O device or memory should use this signal to gate data onto the BUS.	
ĪORQ	33	I/O Address Select — A tri-state, active-low processor output control line. IORQ indicates that the address lines hold a valid I/O address for an I/O Read or Write.	
MEMRQ	34	Memory Address Select — A tri-state, active-low memory request line. MEMRQ indicates that the Address Bus holds a valid address for memory read or memory write operations.	
IOEXP	35	I/O Expansion — An active-low control signal used to expand or enable I/O Port addressing.	
MEMEX	36	Memory Expansion — An active-low control signal used to expand or enable memory addressing.	
REFRESH	37	Dynamic Memory Refresh — a tri-state, active-low control line normally used to refresh dynamic memory. This signal is not generated on this processor card.	
MCSYNC	38	Machine Cycle Sync — A tri-state, active-low processor output signal that occurs once during each processor machine cycle. (Machine cycle is defined as the sequence that involves Addressing, Data Transfer and Execution.) MCSYNC defines the beginning of the machine cycle.	
STATUS 1	39	Status Control Line 1 — Used in conjunction with STATUS 0 to indicate the type of CPU cycle in progress.	

TABLE 3. ISB-3110 STD BUS Signal Functions (Continued)

SIGNAL	PIN NO.	FUNCTIONAL DESCRIPTION	
STATUS 0	40	Status Control Line 0 — Used in conjunction with STATUS 1 to indicate the type of CPU cycle in progress.	
BUSAK	41	BUS Acknowledge — An active-low output line. The processor responds to a BUSRQ by releasing the BUS and giving an Acknowledge signal on the BUSAK line. BUSAK occurs at the completion of the current machine cycle.	
BUSRQ	42	Bus Request — An active-low input line. A BUSRQ causes the processor to suspend operations on the BUS by releasing all tri-state BUS lines for use by another processor. The BUS is released once the current machine cycle is completed.	
INTAK	43	Interrupt Acknowledge — An active-low output line from the processor card that occurs in response to (INTRQ). It is used to tell the interrupting device that the processor card is ready to respond to the Interrupt. For vectored interrupts the vector address is placed on the Data Bus by the interrupting device during INTAK.	
INTRO	44	Interrupt Request — An active-low processor card input line that conditionally interrupts the program. It is masked and ignored by the processor unless deliberately enabled by a program instruction. If the processor accepts the interrupt, it acknowledges by dropping INTAK.	
WAITRO	45	Wait Request — An active-low input line to the processor that suspends processor operations as long as it remains low. The processor will hold in a state that maintains a Valid Address on the Address Bus.	
NMIRQ	46	Non-Maskable Interrupt — An active-low processor card interrupt input line of highest priorit	
SYSRESET	47	System Reset — An active-low output from the system reset circuit. The system reset circuit is triggered by power-on detection or by the pushbutton reset. The system reset bus line should be applied to all cards on the BUS that have latch circuits requiring initialization.	
PBRESET	48	Push Button Reset — An active-low input line to the processor.	
CLOCK	49	Clock From Processor — A buffered processor clock signal used for system synchronization or as a general clock source.	
CNTRL	50	Control — An external clock input for special clock timing.	
PCO	51	Priority Chain Output (Output, active-high) — This signal is sent to the PCI input of the next lower card in the priority chain. A card that needs priority should hold PCO low.	
PCI	52	Priority Chain In (Input, active-high) — This signal is provided directly from the PCO of the next higher card in the priority chain. A high level on PCI gives priority to the card sensing the PCI input.	
AUX GND	53 & 54	Auxiliary Ground — Ground for AUX Power. Both pins bussed together for current capacity.	
AUX +V	55	Auxiliary Positive Voltage (+12 Volts DC)	
AUX –V	56	Auxiliary Negative Voltage (-12 Volts DC)	

TABLE 4. ISB-3110 AC Characteristics

		8085	A-2 <sup>[2]</sup>
SYMBOL	PARAMETER	(PRELIM)	
	O to sour administration of E	MIN (ns)	MA> (ns)
tcyc	CLK Cycle Period	200	2000
t <sub>1</sub>	CLK Low Time	40	T anil
t <sub>2</sub>	CLK High Time	70	
t <sub>r</sub> , t <sub>f</sub>	CLK Rise and Fall Time		30
t <sub>AC</sub>	A <sub>8-15</sub> Valid to Leading Edge of Control <sup>[1]</sup>	115	encou. Tentil
tACL	A <sub>0-7</sub> Valid to Leading Edge of Control	115	
t <sub>AD</sub>	A <sub>0-15</sub> Valid to Valid Data In	avi accur are easur Na	350
t <sub>AFR</sub>	Address Float After Leading Edge of READ (INTA)	sit 1838 Ing 1688	0
tAL	A <sub>8-15</sub> Valid Before Trailing Edge of SYNC <sup>[2]</sup>	50	
tALL	A <sub>0-7</sub> Valid Before Trailing Edge of SYNC	50	Milosi V
tary	WAIT Valid from Address Valid		100
tcA	Address (A <sub>8-15</sub> ) Valid After Control	60	
tcc	Width of Control Low (RD, WR, INTA) Edge of SYNC	230	est eve
tCL	Trailing Edge of Control of SYNC	25	\$ MA
t <sub>DW</sub>	Data Valid to Trailing Edge of WRITE	230	
tHABE	BUSAK to Bus Enable	grifetid st	150
tHABF	Bus Float After BUSAK		150
tHACK	BUSAK Valid to Trailing Edge of CLK	40	
t <sub>HDH</sub>	BUSRQ Hold Time	0	
tHDS	BUSRQ Setup Time to Trailing Edge of CLK	120	i anal
tINH	INTR Hold Time	0	
t <sub>INS</sub>	INTR, Setup Time to Falling Edge of CLK	150	

0)/44==-	OH H	8085A-2 <sup>[2]</sup> (PRELIM)	
SYMBOL	PARAMETER	MIN (ns)	MAX (ns)
tLA	Address Hold Time After SYNC	50	
t <sub>LC</sub>	Trailing Edge of SYNC to Leading Edge of Control	60	
tLCK	SYNC High During CLK Low	50	
t <sub>LDR</sub>	SYNC to Valid Data During Read		270
t <sub>LDW</sub>	SYNC to Valid Data During Write		120
t <sub>LL</sub>	SYNC Width	80	
t <sub>LRY</sub>	SYNC to READY Stable		30
tRAE	Trailing Edge of READ to Re-Enabling of Address	90	
t <sub>RD</sub>	READ (or INTA) to Valid Data		150
t <sub>RV</sub>	Control Trailing Edge to Leading Edge of Next Control	220	
t <sub>RDH</sub>	Data Hold Time After READ INTA	0	
t <sub>RYH</sub>	WAIT Hold Time	0	
tRHS	WAIT Setup Time to Leading Edge of CLK		
t <sub>WD</sub>	Data Valid After Trailing Edge of WRITE	60	
t <sub>WDL</sub>	LEADING Edge of WRITE to Data Valid		20

#### Notes

- 1. A8-A<sub>15</sub> address Specs apply to IO/M, S<sub>0</sub>, and S<sub>1</sub> except A8-A<sub>15</sub> are undefined during T<sub>4</sub>-T<sub>6</sub> of OF cycle whereas  $\overline{\text{MREQ}}$ ,  $\overline{\text{IORQ}}$  and S<sub>1</sub> are stable.
- 2. Test conditions:  $t_{CYC}$  = 320ns (8085A)/200ns (8085A-2);  $C_L$  = 150pF.
- 3. For all output timing where  $C_L$  = 150pF use the following correction factors:

 $25pF \le C_L < 150pF$ : -0.10ns/pF $150pF < C_L \le 300pF$ : +0.30ns/pF

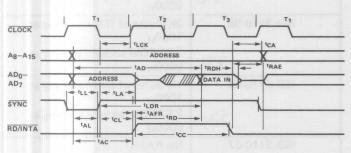
- 4. Output timings are measured with purely capacitive load.
- 5. All timings are measured at output voltage  $V_L$  = 0.8V,  $V_H$  = 2.0V, and 1.5V with 20ns rise and fall time on inputs.
- 6. To calculate timing specifications at other values of  $t_{\mbox{\footnotesize{CYC}}},$  use Table 5.

TABLE 5. ISB-3110 Timing Equations

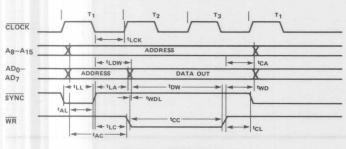
SYMBOL	EQUATIONS	LIMIT
tAL	(1/2) T - 50	Min.
t <sub>LA</sub>	(1/2)T - 50	Min.
t <sub>LL</sub>	(1/2) T - 20	Min.
tLCK	(1/2) T - 50	Min.
tLC	(1/2) T - 40	Min.
t <sub>AD</sub>	(5/2 + N) T - 150	Max
t <sub>RD</sub>	(3/2 + N) T - 150	Max
t <sub>RAE</sub>	(1/2) T - 10	Min.
tca	(1/2) T - 40	Min.
t <sub>DW</sub>	(3/2 + N) T - 70	Min.
twp	(1/2) T - 40	Min.

SYMBOL	EQUATIONS	LIMIT
tcc	(3/2 + N) T - 70	Min.
tcL	(1/2) T - 75	Min.
tary	(3/2) T - 200	Max.
tHACK	(1/2) T - 60	Min.
tHABF	(1/2) T + 50	Max.
tHABE	(1/2) T + 50	Max.
t <sub>AC</sub>	(2/2) T - 85	Min.
t <sub>1</sub>	(1/2) T - 60	Min.
t <sub>2</sub>	(1/2) T - 30	Min.
t <sub>RV</sub>	(3/2) T - 80	Min.
t <sub>LDR</sub>	(4/2) T - 30	Max.
		AND THE RESERVE TO SERVE TO SE

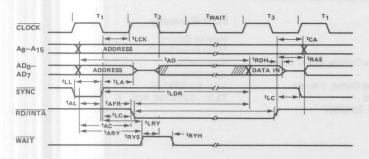
**NOTE:** N is equal to the total WAIT states.  $T = t_{CYC}$ .



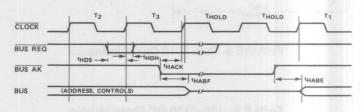
**READ OPERATION** 



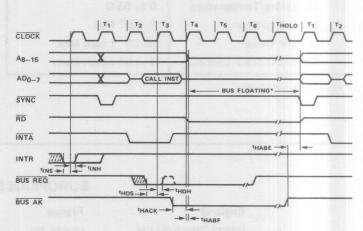
WRITE OPERATION



READ operation with WAIT CYCLE (Typical) (same READY timing applies to WRITE operation)



BUS REQUEST OPERATION



INTERRUPT AND BUS REQUEST

FIGURE 2. ISB-3110 Timing Diagrams

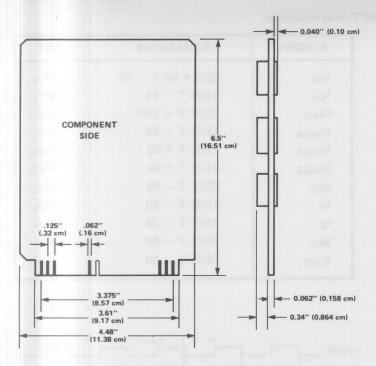


FIGURE 3. ISB-3110 Card Dimensions

TABLE 6. ISB-3110 DC Characteristics

PARAMETER	LIMITS	
Power V <sub>CC</sub>	5V ±5% at 1.5A Max.	
Operating Temperature	0 to 55°C	
Input Loading	1 LS* Max.	
Output Drive	60 LS* Loads Max.	
Output 3-State Leakage	1 LS* Loads Max.	

<sup>\*</sup>Low-power Schottky

#### ORDERING INFORMATION

ORDERING PART NO.	DESCRIPTION
ISB-3110-01	4K Bytes of RAM strapped to start at 1000 <sub>H</sub> Two EPROM sockets strapped to start at 0000 <sub>H</sub>
ISB-3110-02	No internal RAM, one EPROM supplied with first 3 bytes programmed to power-on start the CPU at location E000H
ISB-3110-03	One EPROM with first 3 Bytes programmed to power-on start the CPU at E000 <sub>H</sub> . 2K bytes of RAM mapped at E800 <sub>H</sub> .
ISB-3110-04 370	3K Bytes of RAM starting at 1000 <sub>H</sub> 2 EPROM sockets starting at 0000 <sub>H</sub>
ISB-3110-05	2K Bytes of RAM starting at 1000 <sub>H</sub> 2 EPROM sockets starting at 0000 <sub>H</sub>
ISB-3110-06	1K Bytes of RAM starting at 1000 <sub>H</sub> 2 EPROM sockets starting at 0000 <sub>H</sub>
ISB-3110-07	No RAMs 2 EPROM sockets starting at 0000 <sub>H</sub>

### **EUROPEAN SALES OFFICES**

#### **England**

Intersil Datel (UK) Ltd. 9th Floor Snamprogetti House Basing View Basingstoke RG21 2YS Hampshire, England Tel: 0256-57361 TLX: 858041 INTRSL G

#### France

Intersil, Inc. Liaison Office 217, Bureaux de la Colline de St. Cloud Batiment D 92213 Saint-Cloud Cedex, France Tel: (1) 602.58.98 TLX: DATELEM 204280F

#### West Germany

Intersil GmbH 8000 Munchen 2 Bavariaring 8 West Germany Tel: 89/539271 TLX: 5215736 INSL D



Systems Division

1275 Hammerwood Ave., Sunnyvale, CA 94086 (408) 743-4442 TWX: 910-339-9369

Intersil cannot assume responsibility for use of any circuitry described other than circuitry entirely embodied in an Intersil product. No other circuit patent licenses are implied. Intersil reserves the right to change the circuitry and specifications without notice at any time.